AN-2025-02: Proper Devices Handling Guideline

1.1 Introduction

This guide includes essential information for handling memory modules and SSDs, including proper techniques for holding, inserting and removing the products from sockets. Adhering to these guidelines at all times will help ensure prolonged and reliable operation of Intelligent Memory (IM) products.

1.2 Reference

- IPC-A-610 Acceptability of Electronic Assemblies

1.3 Definitions

Electrostatic Discharge (ESD)

- Rapid transfer of a static electric charge from one object to another of a different potential that was created from electrostatic sources. When an electrostatic charge is allowed to come in contact with or close to a sensitive component, it can cause damage to the component.

1.4 ESD Precautions

To prevent electrostatic discharge (ESD) damage when handling memory modules or SSDs, it is important to wear an anti-ESD wrist strap that is properly grounded. This includes removal from the ESD-marked protective shipping container/bag, or during installation/removal from sockets.

Figure 1: Proper way to wear anti-ESD wrist straps

Figure 2: Wrong way to wear anti-ESD wrist straps

1.5 Handling consideration – Contamination

- Wear clean gloves or finger cots that maintain EOS/ESD protection
- Wear solvent resistant gloves meeting all EOS/ESD requirements during cleaning procedures

1.6 Proper way to hold a memory module/SSD

- Grip the non-connector edge or side of a module or an SSD gently
- Do not hold two or more modules or SSDs together

- Do not drop a module or an SSD
- Do not twist or bend a module or an SSD
- Do not stack two or more modules or SSDs
- Do not press on the side or on the gold fingers to lift a module or an SSD

Figure 3: Grip the side of the device

Figure 4: Do not hold several devices together

Figure 5: Do not drop a device

Figure 6: Do not twist or bend a device

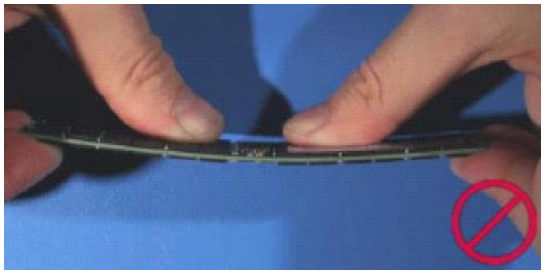


Figure 7: Do not stack two or more devices

Figure 8: Do not press on the side to lift a device

1.7 Proper way to insert or remove SODIMMs

- Gently insert the module into the socket at an angle, inserting the edge with gold fingers first
- Do not press the memory chips during insertion or removal
- Do not insert a module by one side at a time

Figure 9: Insert the module into the socket at an angle

Figure 10: Do not press the memory chips during insertion or removal

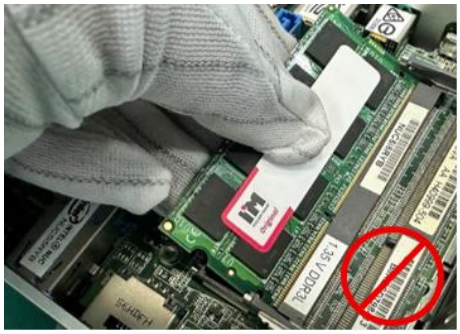
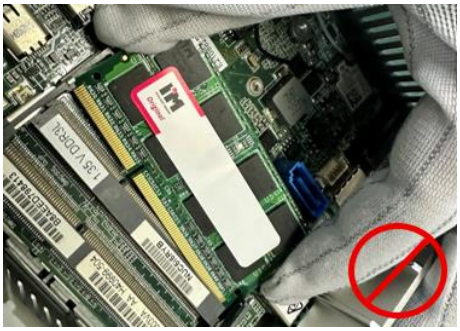


Figure 11: Do not insert a module by one side at a time



1.8 Proper way to insert or remove DIMMs

- Do not press the memory chips during insertion or removal
- Do not insert/remove the memory module at an angle
- Do not insert a module by pushing on one side only
- Do not use one alignment notch alone during removal

Figure 12: Do not press the memory chips during insertion or removal

Figure 13: Do not insert/remove the memory module at angle

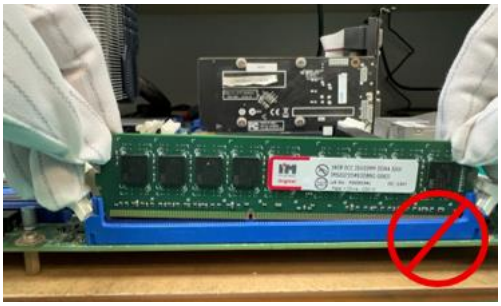


Figure 14: Do not insert a module by pushing on one side only

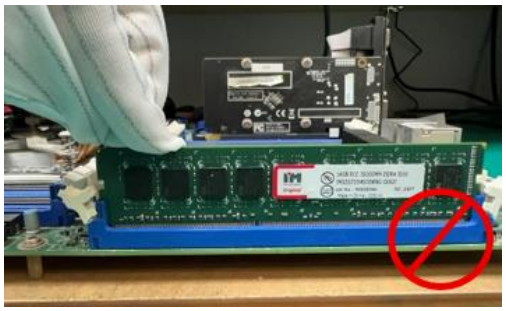
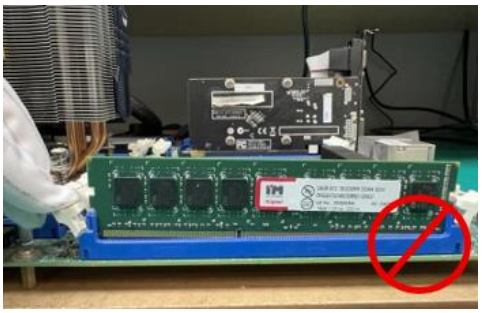


Figure 15: Do not use one alignment notch alone during removal



1.9 Proper way to insert or remove M.2 SSDs

- Do not push the M.2 SSD into the socket sideways

Figure 16: Do not push the M.2 SSD into the socket sideways

Disclaimer

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REVISION HISTORY

Revision	Description	Date
01	Initial release	30-Sep-2025